

Press release

Düsseldorf, 03.11.2025

Kaijo presents new high-speed large area bonder MPB-2000 for the first time at SEMICON Europe

The Japanese Kaijo Corporation has been a leader in the development and manufacturing of wire bonding technologies for over 50 years. At this year's SEMICON Europe, the company is presenting the MPB-2000, a new fully automatic, high-performance Thermosonic Large Area Bonder.

With a bonding area of 290 mm × 290 mm and a maximum substrate size of up to 300 mm × 300 mm, the bonder is suitable for a wide range of applications. The bonder processes gold wires from 15 to 75 µm and copper wires from 15 to 50 µm, achieving bond speeds of 135 ms per wire. With a immersion depth of 30 mm, it meets the requirements for a large number of applications. The vibration-controlled XY table and the strongly damped machine platform ensure the highest bonding quality, even with complex components and a wide variety of materials.

The floating bond head with its large immersion depth enables flexible processing of even large-format substrates up to 300 mm in size. Thanks to the integrated temperature and position correction function, the system adjusts its parameters in real time and ensures the highest bonding quality even in demanding processes. 'With the MPB-2000, Kaijo is setting new standards in productivity, reliability and versatility for electronic assembly and manufacturing, significantly expanding the range of applications in the semiconductor and electronics sectors,' emphasises Jörg Lewandowski, Managing Director of Systech Europe GmbH.

To enable the powerful wire bonder to reach its full potential, the MPB-2000 is optimally tailored to modern manufacturing environments. The SECS/GEM interface enables seamless integration into Industry 4.0 processes. Trade visitors can gain detailed insights into the system at SEMICON Europa 2025 in Hall B2, booth 422.

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About Kaijo Corporation

Kaijo Corporation looks back on more than half a century of innovation in thermosonic bonding technology. Through continuous research, the highest manufacturing quality and practical development work, Kaijo is regarded worldwide as one of the technology leaders in the field of semiconductor bonding technology.

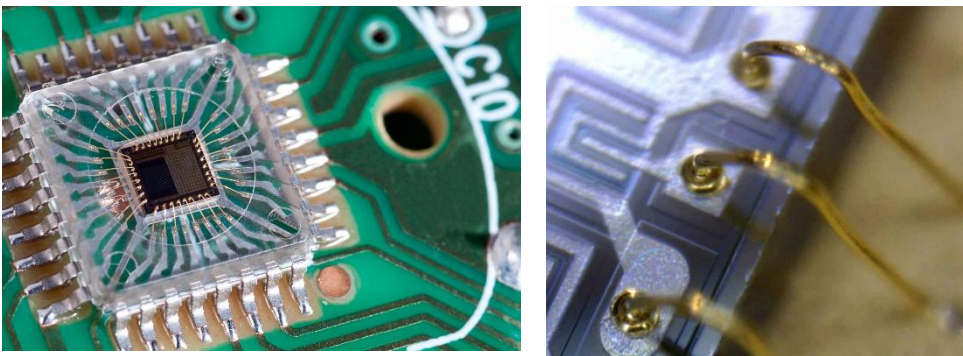
In Europe, the new Kaijo MPB-2000 wire bonder is distributed exclusively by SYSTECH Europe GmbH. The Düsseldorf-based company has been a close partner of Kaijo for many years and has extensive process and application expertise in bonding technology. This close cooperation ensures that customers in Europe receive not only state-of-the-art technology, but also sound technical advice, process support and service of the highest standard.

About SYSTECH Europe

SYSTECH Europe offers comprehensive solutions in the field of test and production systems for the electronics and microelectronics industry. The company has been active on the European market since 1989, supporting its customers with state-of-the-art technologies and flexible systems. With a strong network of partners in Europe and over 48 qualified engineers and technicians in 23 countries, the experts guarantee reliable support, particularly in the field of TAKAYA flying probe systems. The focus is on competent advice, high-quality products and first-class service for more efficient production processes and sustainably increased quality.

Further information is available at: [Systech Europe](http://www.systech-europe.de)

Picture:



Picture caption:

New Kaijo High-Speed Large Area Bonder MPB-2000 for gold and copper wires

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Press release

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